

(2.00 mm) .0787"

MMT SERIES

# HORIZONTAL SURFACE MOUNT HEADER

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com/MMT](http://www.samtec.com/MMT)

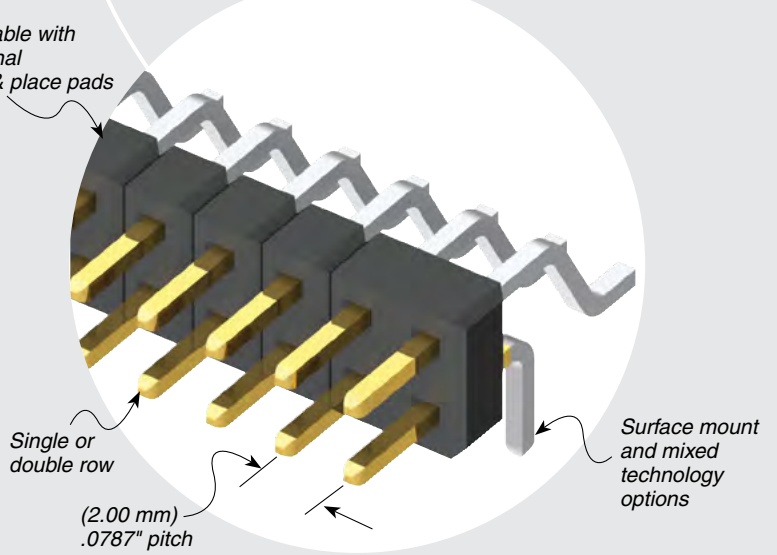
**Insulator Material:**  
Black Liquid Crystal Polymer  
**Terminal Material:**  
Phosphor Bronze  
**Plating:**  
Au or Sn over  
50 μ" (1.27 μm) Ni  
**Operating Temp Range:**  
-55 °C to +105 °C with Tin;  
-55 °C to +125 °C with Gold  
**RoHS Compliant:**  
Yes

**Board Mates:**  
CLT, SQT, SQW, ESQT,  
TLE, SMM, MMS

**Cable Mates:**  
TCSD

Available with optional pick & place pads

## APPLICATIONS



## PROCESSING

**Lead-Free Solderable:**  
Yes  
**SMT Lead Coplanarity:**  
(0.10 mm) .004" max (02-25)  
(0.15 mm) .006" max (26-36)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



## ALSO AVAILABLE (MOQ Required)

- Alignment pins
- Locking clips
- Molded pick & place pads
- Other platings
- Contact Samtec.

MMT	1	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	ROW OPTION	OPTION
		02 thru 36	-01 = (3.20 mm) .126" post  -02 = (4.45 mm) .175" post	-F = Gold flash on post, Matte Tin on tail  -L = 10 μ" (0.25 μm) Gold post, Matte Tin on tail  -T = Matte Tin	-SH = Single Row  -DH = Double Row  -MT = Double Row Mixed Technology	-K = (4.00 mm) .157" DIA Polyimide Film Pick & Place Pad (3 positions minimum)  -P = Pick & Place Pad (2 positions minimum)  -"XXX" = Polarized Position Specify position of omitted pin  -TR = Tape & Reel Packaging

**Note:** Some lengths, styles and options are non-standard, non-returnable.